

IWR6432 Device Silicon Errata

Silicon Revisions 1.0 and 2.0



ABSTRACT

This document describes the known exceptions to the functional specifications (advisories). This document may also contain usage notes. Usage notes describe situations where the device's behavior may not match the presumed or documented behavior. This may include behaviors that affect device performance or functional correctness.

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1 Introduction

This document describes the known exceptions to the functional and performance specifications to TI CMOS Radar Devices (IWRL6432)

2 Device Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of Radar / mmWave sensor devices. Each of the Radar devices has one of the two prefixes: XIx or IWRLx (for example: **XI6432 BGABL**). These prefixes represent evolutionary stages of product development from engineering prototypes (XI) through fully qualified production devices (IWRL).

Device development evolutionary flow:

- XI** — Experimental device that is not necessarily representative of the final device's electrical specifications and may not use production assembly flow.
- IWRL** — Production version of the silicon die that is fully qualified.

XI devices are shipped with the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

Texas Instruments recommends that these devices not to be used in any production system as their expected end –use failure rate is still undefined.

3 Device Markings

Figure 3-1 shows an example of the IWRL6432 Radar Device's package symbolization.

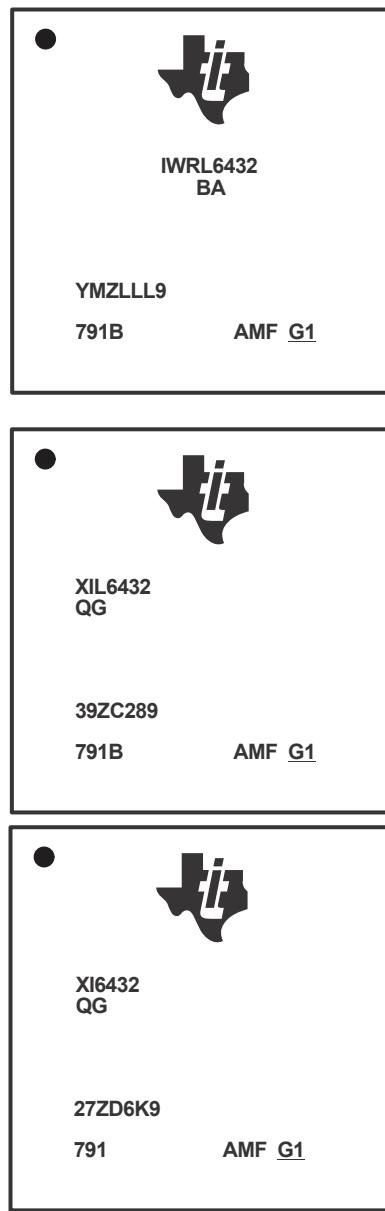


Figure 3-1. Example of Device Part Markings

This identifying number contains the following information:

- **Line 1:** TI Logo
- **Line 1:** Device Number
- **Line 2:** Safety Level and Security Grade
 - Q = Non-Functional Safety
 - B = SIL 2
 - G = General
 - A = Authenticated boot
- **Line 3:** Lot Trace Code
 - YM = Year/Month Code
 - Z = Assembly Site Code

Device Markings

- LLL = Assembly Lot
- 9 = Primary Site Code
- **Line 4:**
 - 791 = IWRL6432 Identifier
 - B = Die Revision
 - AMF = Package Identifier
 - G1 = "Green" Package Build (must be underlined)

4 Usage Notes

4.1 Power up sequence in power optimized topology

When the device is in power optimized topology and 1.8V powers up before 1.2V, a momentary large current can be seen at 1.2V rail before NRESET release only during the device power up. To avoid that, power up 1.2V (VDDIN, VDD_SRAM and VNWA) before 1.8V .

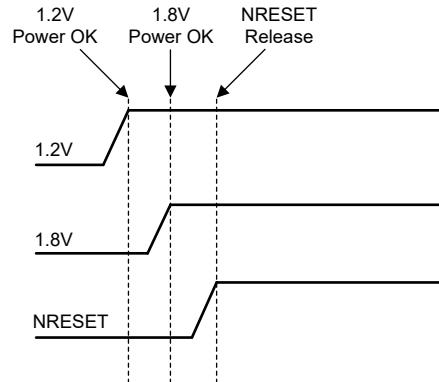


Figure 4-1. Recommended power up sequence

Note

1. This usage note is ONLY applicable for 1.2V rail. For signals other than 1.2V power supply, refer to the "Device Wake-up Sequence" diagram in the data sheet.
2. The power distribution network in TI EVM/Reference designs follows "Device Wake-up Sequence" in the data sheet and supports the additional current without powering up 1.2V first.

4.2 Meeting data sheet spec for 1.2V Digital LDO output path in BOM optimized topology

As indicated in the device data sheet, 1.2V Digital LDO requires one decoupling capacitor with a typical value of 4.7uF. The parasitic offered by different portion of the output path is illustrated in Figure 4-2. "RT1" and "RT2" are parasitic resistances offered by the ball to capacitor lead trace and the ground trace, respectively. Similarly, "LT1" and "LT2" are parasitic inductances offered by the ball to capacitor lead trace and the ground trace, respectively. "ESL1" and "ESR1" are the effective series inductance and resistance of the decoupling capacitor. Table 4-1 gives the minimum, maximum and typical values of the capacitance and the parasitic.

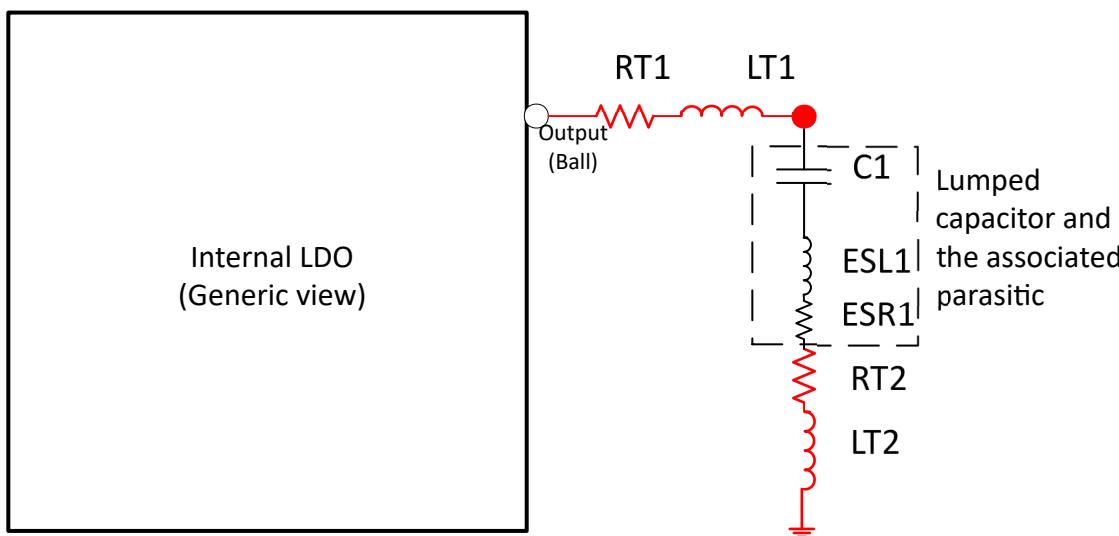


Figure 4-2. Single decoupling capacitor associated PCB parasitic

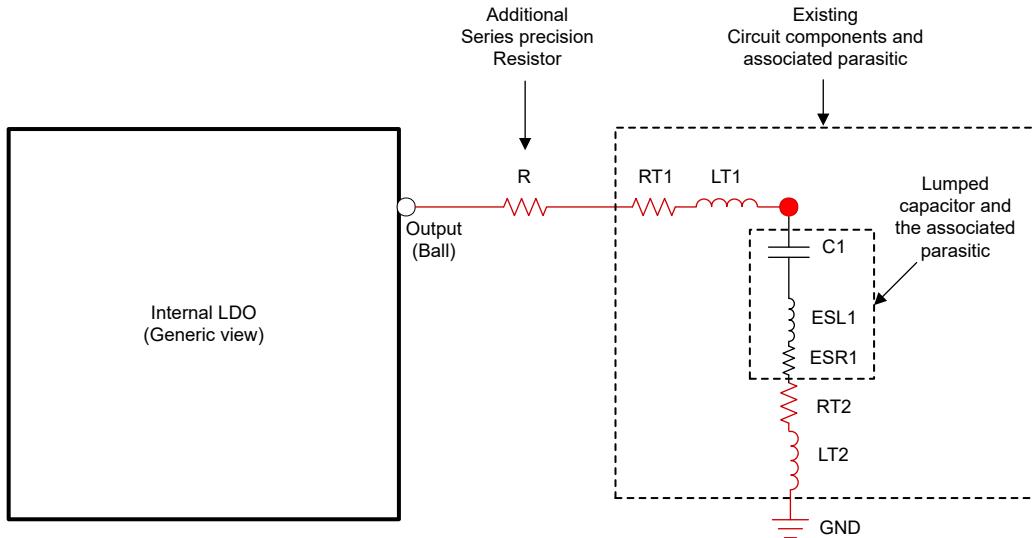
Table 4-1. 1.2V Dig LDO Output

	Min	Typ	Max	Unit
Recommended value of C	3.6	4.7	5.2	uF
Allowed output parasitic inductance L _p	1	1.5	2	nH
Allowed output parasitic resistance R_p	15	20	35	mOhm

If the R_p is not achievable in PCB design, below workarounds can be considered:

Add a series precision resistor in the VDD output path along with the decoupling capacitor to get equivalent effective series resistance of the output path within the data sheet limits.

Example part no.: PA0402FRL570R02L, 20mOhm, 1% Tol.; MFL0603R0200FA, 20mOhm, 1% Tol;

**Figure 4-3. Example workaround**

5 Advisory to Silicon Variant / Revision Map

Table 5-1. Advisory to Silicon Variant / Revision Map

Advisory Number	Advisory Title	IWRL6432	IWRL6432
		ES1.0	ES2.0
Analog / Millimeter Wave			
ANA #48	Reduction in supported RF frequency range	x	
ANA #49	Analog temperature sensor: Not usable at high temperatures	x	
ANA #50	GPADC based external signal monitor is not supported	x	
ANA #51	Continuous Wave Streaming CZ mode: Sudden jump in RX output codes every 20.97152msec	x	x
ANA #52	Slicer LDO Test LOAD (TLOAD) not disabled after startup	x	
ANA #57	SNR degradation at 60GHz in the presence of strong near range reflector	x	x
Digital Subsystem			
DIG #1	ePWM: Glitch during Chopper mode of operation	x	x
DIG #2	UART A cannot be used to wake up the sequencer from Deep Sleep Low Power Mode	x	
DIG #3	Limited UART baud rates	x	x
DIG #4	RS232 AutoBaud Rate feature doesn't support trimmed ROCSC variation.	x	x
DIG #5	Internal Bus access to SPI for data transfer not supported when SPI smart-idle mode is enabled.	x	x
DIG #6	CRC: CRC 8-bit data width and CRC8-SAE-J1850 and CRC8-H2F possible use in CAN module is not supported	x	x
DIG #7	APPSS Cortex-M4 doesn't get the correct error response when cluster 3 retention memories are accessed in low-power deep-sleep powered down state	x	
DIG #8	Shared RAM clock gating default values	x	x
DIG #9	TOP_IO_MUX register space not accessible from RS232 for debug purposes.	x	x
DIG #10	Incorrect behavior of frame stop API	x	x
DIG #14	Corrupted Data Store for Partial Write in Shared Memory	x	x
DIG #15	Boot failure, if metainimage is multiple of 2K		x
DIG #16	Boot failure for images less than size 8k over SPI	x	x

6 Known Design Exceptions to Functional Specifications

ANA #48***Reduction in supported RF frequency range*****Revision(s)
Affected:**

IWRL6432 ES1.0

Description:

Supported frequency range in this version of silicon is 58 - 62.5GHz. Will be enhanced in the future.

Workaround

The operating chirp frequency should be restricted from 58GHz to 62.5GHz.

**Revision(s)
Affected:**

IWRL6432 ES2.0

Description:

Supported frequency range in this version of silicon is 57 - 63.9GHz.

Workaround

The operating chirp frequency should be restricted from 57GHz to 63.9GHz.

ANA #49 *Analog temperature sensor: Not usable at high temperatures*

Revision(s) Affected IWRL6432 ES1.0

Details	Leakage current paths have been identified along the routing path to GPADC. The analog temperature sensor are not usable at high temperatures due to this issue.
Workaround	Use digital temperature sensor readings to get an estimate of the die temperature. This has been fixed in ES2.0

ANA #50	<i>GPADC based external signal monitor is not supported</i>
Revision(s) Affected	IWR6432 ES1.0
Details	<p>Leakage current paths have been identified along the routing path to GPADC.</p> <p>GPADC based external signal monitoring is not usable due to this issue.</p>
Workaround	<p>Only use external monitoring for voltages lower than 0.4V</p> <p>This has been fixed in ES2.0</p>
ANA #51	<i>Continuous Wave Streaming CZ mode: Sudden jump in RX output codes every 20.97152 msec</i>
Revisions Affected	IWR6432 ES1.0, ES2.0
Details	<p>On Continuous Wave Streaming CZ mode, the Rx data shows a sudden jump in output codes every 20.97152 milliseconds.</p> <p>This is not an issue in the Radar Functional mode when chirps are used. However, this issue is seen when testing Rx chain in lab using continuous stream mode.</p>
Workaround	<p>To use Continuous stream (CW) mode for testing, TI recommends to start data capturing from the first sample to make sure the glitch occurs at deterministic samples. Please follow the below sequence to achieve this:</p> <ul style="list-style-type: none"> • Configure the RDIF (Radar Data Interface) • Arm the DCA1000 (Data capture card) • Enable the continuous stream mode. <p>The glitch will not be seen with this sequence. For example, if the user analyzes first 20ms of data or between 21 and 41ms.</p>

ANA #52***Slicer LDO Test LOAD (TLOAD) not disabled after startup***

Revisions Affected

IWRL6432 ES1.0

Details

By default, the slicer LDO TLOAD is enabled during startup for stability purposes. After the oscillator is enabled, the current loading should be disabled automatically to reduce power and extend reliability.

Since presently the loading is not turned OFF automatically, higher than expected current is observed ($\approx 8\text{mA}$).

Workaround

It is recommended to disable the load bit explicitly by setting the following field to save unnecessary power burnout :

TOP_PRCM: CLK_CTRL_REG1_LDO_CLKTOP = 0x1

This has been fixed in ES2.0

ANA #57***SNR degradation at 60GHz in the presence of strong near range reflector***

Revision(s) Affected

IWRL6432 ES1.0, ES2.0

Details

There is a non-linearity of the synthesizer when crossing 60GHz which causes increased noise floor at RX output in the presence of a strong near range reflector.

Workaround

Chirps with large RF bandwidth ($> 1.5\text{GHz}$) have negligible noise floor impact. For lower bandwidth chirps, avoid 60GHz.

DIG #1 **ePWM: Glitch during Chopper mode of operation**
Revisions Affected IWRL6432 ES1.0, ES2.0

Details During chopper mode operation, a glitch can be observed on the ePWMA and ePWMB output signals from the ePWM module.

Workaround If the use case is impacted by a glitch, TI recommends to disable the PWM chopper control function by setting the LPRADAR:APP_PWM:PCCTL:CHPEN register bit to 0.

The below table shows the Register Address for above workaround.

Bits	Name	Address
0	LPRADAR:APP_PWM:PCCTL:CHP EN	0X57F7 FC3C

DIG #2	<i>UART: UARTA cannot be used to wake up the sequencer from Deep Sleep Low Power Mode</i>
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Revision(s) Affected	IWRL6432 ES1.0
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Details	Universal Asynchronous Receiver-Transmitter A (UART A) cannot be used to wake up the processor core from Deep-Sleep mode. Currently UART B interrupts are connected to Wake-up Interrupt Controller lines.
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Workaround	<p>It is recommended to use other wake-up sources (Controller Area Network - Flexible Data-rate (CAN-FD)/ UARTB/ Serial Peripheral Interface(SPI))</p> <p>This has been fixed in ES2.0.</p>
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DIG #3
UART: Limited UART baud rates
Revisions Affected

IWRL6432 ES1.0, ES2.0

Details

Due to a design limitation (related to the clocking scheme), UART doesn't support standard baud rates above 115200 bits per second. Higher baud rates up to 1.25Mbps can be supported but the rates are non-standard.

Applications requiring UART cannot use standard baud rates above 115200 bits per second

Standard Baud Rates supported :

XTAL (MHz)	40	
Ideal Baud rate (bps)	Actual Baud	Error %
115200	113636.36	1.36
76800	75757.58	1.36

Non- Standard baud rates supported:

XTAL (MHz)	40
Maximum baud (bps)	1250k
	833.33k
	625k
	500k
	416.66k
	357.14k
	312.5k

Workaround

TI recommends to use the following workarounds based on application needs:

- Use of non-standard baud rates can provide up to 1.25Mbps throughput, if external MCU can support the same non-standard baud rates.
- Use SPI instead, if use-case needs higher throughput.

DIG #4

RS232: Auto Baud Rate feature doesn't support trimmed RCOSC variation

Revisions Affected

IWRL6432 ES1.0, ES2.0

Details

Once RCOSC is trimmed, the expected clock frequency and the variation observed in frequency (tolerance on RC clock) do not support the required Auto Baud rate setting for RS232.

Currently Auto Baud is disabled by default for 64xx ES2.0

DIG #5	<i>Internal Bus access to SPI for data transfer not supported when SPI smart-idle mode is enabled.</i>
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Revisions Affected	IWR6432 ES1.0, ES2.0
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Details	Smart-idle mode needs to be disabled for SPI before the first trigger for data transfer access. If the SPI smart-idle mode is required to be enabled, the mode has to be enabled again once the access is complete.
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Workaround	<p>TI recommends to follow the below sequence:</p> <p>Auto Wake-up = 1 & Controller mode</p> <ol style="list-style-type: none"> 1. Configure McSPI as required 2. Enable SmartIdle (by setting LPRADAR:APP_CTRL:SPI1_SMART_IDLE_ENABLE for SPI1 and LPRADAR:APP_CTRL:SPI2_SMART_IDLE_ENABLE for SPI 2)after making sure that there is no pending transaction from/to SPI or any more access to be done to McSPI by CPU or DMA 3. If any register or memory access to McSPI has to be done, disable SmartIDLE mode (by setting LPRADAR:APP_CTRL:SPI1_SMART_IDLE_ENABLE=0 for SPI 1 and LPRADAR:APP_CTRL:SPI2_SMART_IDLE_ENABLE =0 for SPI 2) 4. In Controller mode, the external host is not going to toggle the SPI_CS, hence there is not any wakeup => there is no difference between (LPRADAR:APP_CTRL:SPI1_SMART_IDLE_AUTO_EN is 1 or 0 for SPI 1 and LPRADAR:APP_CTRL:SPI2_SMART_IDLE_AUTO_EN is 1 or 0) <p>Auto Wake-up = 1 & Peripheral mode</p> <ol style="list-style-type: none"> 1. Configure McSPI as required 2. Enable SmartIdle (by setting LPRADAR:APP_CTRL:SPI1_SMART_IDLE_ENABLE for SPI1 and LPRADAR:APP_CTRL:SPI2_SMART_IDLE_ENABLE for SPI 2) after making sure that there is no pending transaction from/to SPI or any more access to be done to McSPI by CPU or DMA 3. If any register or memory access to McSPI has to be done by any controller (DMA / CPU), disable SmartIDLE mode (by setting LPRADAR:APP_CTRL:SPI1_SMART_IDLE_ENABLE=0 for SPI 1 and LPRADAR:APP_CTRL:SPI2_SMART_IDLE_ENABLE =0 for SPI 2) 4. If there is wakeup from McSPI (because of some SPI_CS toggle), then the clock is automatically enabled. 5. Disable SmartIdle configuration (by setting LPRADAR:APP_CTRL:SPI1_SMART_IDLE_ENABLE=0 for SPI 1 and LPRADAR:APP_CTRL:SPI2_SMART_IDLE_ENABLE =0 for SPI 2) to do the register access.
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The below table shows the Register Addresses for above workaround.

Bits	Name	Address
0	LPRADAR:APP_CTRL:SPI1_SMART_IDLE_ENABLE	0x560603A8
2	LPRADAR:APP_CTRL:SPI1_SMART_IDLE_AUTO_EN	0x560603A8
0	LPRADAR:APP_CTRL:SPI2_SMART_IDLE_ENABLE	0x560603AC

- DIG #5** (continued) ***Internal Bus access to SPI for data transfer not supported when SPI smart-idle mode is enabled.***

2	LPRADAR:APP_CTRL:SPI2_SMAR T_IDLE_AUTO_EN	0x560603AC
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DIG #6	<i>CRC: CRC 8-bit data width and CRC8-SAE-J1850 and CRC8-H2F possible use in CAN module is not supported</i>
Revisions Affected	IWR6432 ES1.0, ES2.0
Details	<ol style="list-style-type: none">1. 8-bit data width is not supported. Minimum data width supported is 16-bit.2. CRC types CRC8-SAE-J1850 and CRC8-H2F are not supported.
Workaround	<ol style="list-style-type: none">1. 16/32/64-bit data widths are supported.2. TI recommends to not use the above mentioned unsupported polynomials.

DIG #7	<i>APPSS Cortex-M4F doesn't get the correct error response when cluster 3 retention memories are accessed in low-power deep-sleep powered down state</i>
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Revision(s) Affected	IWRL6432 ES1.0
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Details	The logic to generate error when Cortex-M4F tries to access cluster 3 memories in powered down state is incorrect due to which Cortex-M4F doesn't get the correct error response.
Workaround	<p>Software shouldn't try to access cluster 3 retention memories during low-power deep-sleep powered down state</p> <p>This has been fixed in ES2.0.</p>

DIG #8 **Shared RAM clock gating default values**
Revision(s) Affected IWRL6432 ES1.0, ES2.0

Details

Possibility of Shared RAM data corruption while exiting from deep sleep mode when clock gating registers are not reprogrammed.

The reset value for Front End Controller Sub System (FECSS), Application Sub System (APPSS) and Hardware Accelerator Sub System (HWASS) shared memory clock gate control is 1. The clock ICG controls are coming from the following registers.

Bits	Name	Address
0	LPRADAR:FEC_CTRL:FECSS_SHARED_MEM_CLK_GATE : FECSS_SHARED_MEM_CLK_GATE_HWA_ENABLE	0x5200002C
0	LPRADAR:APP_CTRL:APPSS_SHARED_MEM_CLK_GATE:APPSS_SHARED_MEM_CLK_GATE_MEM0_HWA_ENABLE	0x56060398
2	LPRADAR:APP_CTRL:APPSS_SHARED_MEM_CLK_GATE:APPSS_SHARED_MEM_CLK_GATE_MEM1_HWA_ENABLE	0x56060398

When APPSS tries to access shared memory bank 0 via VBUSM SCR while FECSS is accessing shared memory via AHB, wrong read values of zero from the shared RAM on the APPSS is observed.

If only one of the clock gates (either HWA or FEC/APP) is enabled based on the allocation, the data is read correctly. Since the clock gating controls are coming from control registers space, these values get reset again and hence needs to be re-programmed after every deep sleep exit.

Workaround

Program ICG controls of clock reaching to shared memory based on different shared memory configuration. The ICG control needs to be re-programmed after every deep sleep exit too.

Configuration	Software care-about
Memory is shared with M3	Disable the following ICG control :- LPRADAR:FEC_CTRL:FECSS_SHARED_MEM_CLK_GATE : FECSS_SHARED_MEM_CLK_GATE_HWA_ENABLE
First 128kb is shared with M4	Disable the following ICG control :- LPRADAR:APP_CTRL:APPSS_SHARED_MEM_CLK_GATE:APPSS_SHARED_MEM_CLK_GATE_MEM0_HWA_ENABLE

DIG #8 (continued)

Shared RAM clock gating default values

256kb is shared with M4	Disable the following ICG controls :- <ul style="list-style-type: none">• LPRADAR:APP_CTRL:APPSS_SHARED_MEM_CLK_GATE:APPSS_SHARED_MEM_CLK_GATE_MEM0_HWA_ENABLE• LPRADAR:APP_CTRL:APPSS_SHARED_MEM_CLK_GATE:APPSS_SHARED_MEM_CLK_GATE_MEM1_HWA_ENABLE
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DIG #9 *TOP_IO_MUX register space not accessible from RS232 for debug purposes*
Revisions Affected IWRL6432 ES1.0, ES2.0

Details RS232 is not able to write TOP_IO_MUX registers unless the space is programmed for user mode access.

Workaround TI recommends to use the following sequence:

1. From Processor or DAP : Unlock TOP_IO_MUX registers (by programming LPRADAR:TOP_IO_MUX:IOCFGKICK0 = 83E7 0B13h and LPRADAR:TOP_IO_MUX:IOCFGKICK1 = 95A4 F1E0h)
2. From Processor or DAP : Write to TOP_IO_MUX registers, LPRADAR:TOP_IO_MUX:USERMODEEN should be set to 0xADADADAD
3. Now TOP_IO_MUX registers can be accessed from RS232.

The below table shows the Register Addresses for above workaround.

Bits	Name	Address
0:31	LPRADAR:TOP_IO_MUX:IOCFGKI CK0	0x5A000068
0:31	LPRADAR:TOP_IO_MUX:IOCFGKI CK	0x5A00006C
0:31	LPRADAR:TOP_IO_MUX:USERM ODEEN	0x5A000060

DIG #10 *Incorrect behavior of frame stop API***Revisions Affected** IWRL6432 ES1.0, ES2.0**Details** The Frame Timer latches Frame Stop command in hardware registers which takes affect at the end of current frame. Frame Stop API issued when Frame Timer has already stopped results in unintended stop in the next frame trigger because of the latched stop bit.**Workaround**

1. Avoid unnecessary Sensor Stop API.
2. The application can have to wait for one complete frame period before getting frame stop.
3. Application waits for FECSS to complete Burst End and Frame End activities after receiving the Frame Stop conformation.

DIG #14**Corrupted Data Store for Partial Write in Shared Memory****Revision(s) Affected**

IWRL6432 ES1.0, ES2.0

Details

Internal shared memory has ODD and EVEN banking structure. For a particular address range, partial write (less than 32 bit) to EVEN bank corrupts same address of ODD bank with next data on the bus. When shared memory is allocated to M4/M3, back to back full word write access to location A followed by sub-word write access to location B corrupts data in location A.

When memory is shared with M4/M3, issue is seen in the following address range:

Memory	Address Range
APP_CPU_SHARED_RAM	0x0048 0000 - 0x004B FFFC
FEC_CPU_SHARED_RAM	0x2120 8000 - 0x2121 FFFC

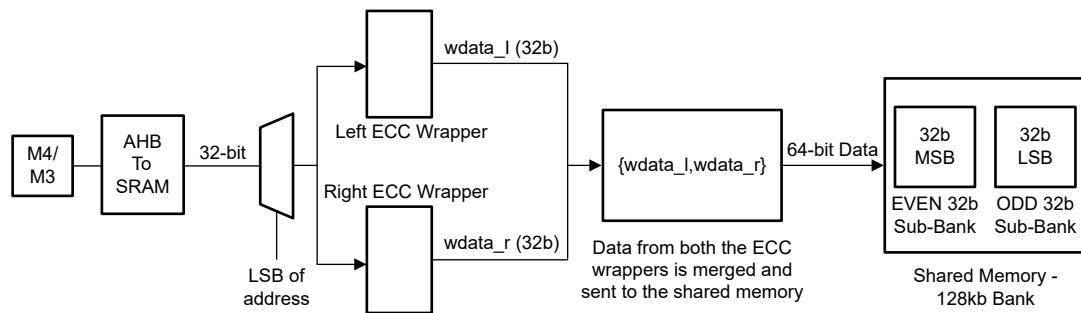


Figure 6-1. Shared Memory Logic Diagram When Shared with M4/M3

When shared with M3/M4, the incoming data bit width is 32 bit as shown in the diagram. So, depending on LSB of address, signals are sent to either left or right ECC wrapper.

Workaround

1. Use shared memories as code memory when shared with processor.
2. Disable ECC for non functional safety devices – ECC is disabled for shared memories in RBL for non functional safety devices.

DIG #15 *Boot failure, if metaimage is multiple of 2K*

Revisions Affected IWRL6432 ES2.0

Details Metaimages that are a multiple of 2048 bytes fail to boot.

Workaround

1. Add a constant non-volatile variable to increase the metaimage size, so that the size is not aligned to 2048 bytes.
2. Update MMWAVE-L-SDK to version 5.4 or above; mmWave LSDK 5.4 and above includes changes to the metaimage generator tool to add a minimal config file (approximately 64 bytes) in case the image is a multiple of 2048 bytes.

DIG #16
Boot failure for images less than size 8k over SPI
Revisions Affected

IWRL6432 ES1.0, ES2.0

Details

The EDMA address linking is not done in few cases (during SPI continuous download), due to which boot fails over SPI continuous download image for the particular metaimage size ranges mentioned in the below table:

Image Size (Bytes)	Issue Present
<2048	No
>2048 & <4096	No
>=4096 & <6144	Yes
>=6144 & <8192	Yes
>=8192	No

Workaround

Use image >8KB for boot over SPI. In case of lower image size, constant data is appended during compile time to create an image >8 KB.

7 Trademarks

All trademarks are the property of their respective owners.

Revision History

Changes from July 25, 2025 to December 15, 2025 (from Revision B (July 2025) to Revision C (December 2025))

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• <i>Advisory to Silicon Variant / Revision Map</i> : Added ANA#57 advisory.....	7

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